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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.: 10/604,164

Applicant(s): Gardecki et al.

Filed.: June 28, 2003

Art Unit: 2823

Dkt. No.: BUR920030026US1

Examiner: Brook Kebede

Title: METHOD FOR FORMING INTERCONNECTS ON THIN WAFERS

Honorable Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450

REQUEST FOR RECONSIDERATION

This Request for Reconsideration is being filed in response to the Final Office Action mailed on March 23, 2005.